PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Kai-Kuang Ho	12/30/2004
Kuo-Ming Chen	12/30/2004

RECEIVING PARTY DATA

Name:	UNITED MICROELECTRONICS CORP.
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park
City:	Hsin-Chu City
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11535987

CORRESPONDENCE DATA

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NAME OF SUBMITTER:	WINSTON HSU

Total Attachments: 2
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CH $40.00 11535987

PATENT

Docket No NAUP0613USA

ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar ($1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

ASSIGNOR(S) (Inventors):

Name: Kai-Kuang Ho Nationality: R.O.C.

Address: 18F-4, No.17, Lane 175, Wu-Ling Rd., Hsin-Chu City, Taiwan, R.O.C.

Name: Kuo-Ming Chen Nationality: R.O.C.

Address: No. 16-1, Community 5, Ta-Lin Tsun, Pei-Pu Hsiang, Hsin-Chu Hsien, Taiwan, R.O.C.

Hereby sells, assigns and transfers to

ASSIGNEE(S):

Name: UNITED MICROELECTRONICS CORP.

Address: No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu City, Taiwan, R.O.C.

and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

"Integrated Die Bumping Process"

Which is found in :

(a) __+__ U.S. patent application executed on even date

(b) _____ U.S. patent application executed on __________

(c) _____ U.S. application serial no. __________

(d) _____ patent no. ________ issued __________

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuation, division, renewal, or substitute thereof, and as to letters patent any reissue or re examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this DEC 30 2004 (Date of signing). (請發明人務必簽署上列日期。)

(Type name of inventor)	**Signature of INVENTOR**
Kai-Kuang Ho	Kai-Kuang Ho
Kuo-Ming Chen	Kuo-Ming Chen

PATENT
RECORDED: 09/28/2006
REEL: 018317 FRAME: 0562